

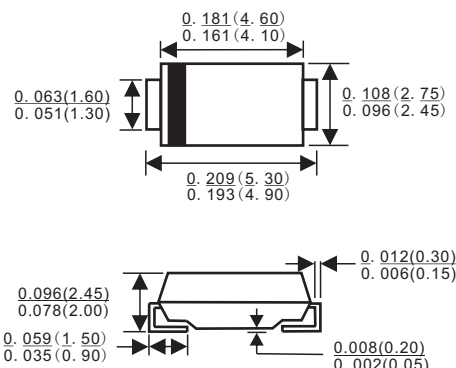
Features

- ✧ For surface mounted application
- ✧ Glass passivated junction chip.
- ✧ Low forward voltage drop
- ✧ High current capability
- ✧ Easy pick and place
- ✧ High surge current capability
- ✧ Plastic material used carries Underwriters Laboratory Classification 94V-0
- ✧ High temperature soldering:
260°C / 10 seconds at terminals

Mechanical Data

- ✧ Case: Molded plastic
- ✧ Polarity: Indicated by cathode band
- ✧ Packaging: 12mm tape
- ✧ Weight: 0.064 gram

SMA/DO-214AC



Dimensions in inches and(millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	S1A	S1B	S1D	S1G	S1J	S1K	S1M	S1T	S1W	S1X	S1Y	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	1300	1600	1800	2000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	760	780	840	900	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	1300	1600	1800	2000	V
Maximum Average Forward Rectified Current @ T _L =110 °C	I _(AV)	1.0											A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	30											A
Maximum Instantaneous Forward Voltage @ 1.0A	V _F	1.1											V
Maximum DC Reverse Current @ T _A =25 °C at Rated DC Blocking Voltage @ T _A =125 °C	I _R	1.0 50											uA uA
Typical Reverse Recovery Time (Note 1)	T _{rr}	1.5											uS
Typical Junction Capacitance (Note 2)	C _j	12											pF
Non-Repetitive Peak Reverse Avalanche Energy at 25°C, I _{AS} =1A, L=10mH	E _{AS}	5											mJ
Typical Thermal Resistance (Note 3)	R _{θJL} R _{θJA}	27 75					30 85					°C/W	
Operating Temperature Range	T _J	-55 to +150											°C
Storage Temperature Range	T _{STG}	-55 to +150											°C

- Notes:
1. Reverse Recovery Test Conditions: $I_F=0.5A$, $I_R=1.0A$, $I_{RR}=0.25A$
 2. Measured at 1 MHz and Applied $V_R=4.0$ Volts
 3. Measured on P.C. Board with 0.2" x 0.2" (5.0mm x 5.0mm) Copper Pad Areas.

RATINGS AND CHARACTERISTIC CURVES (S1A THRU S1M)

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

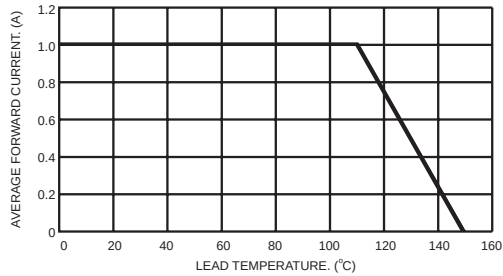


FIG.2- TYPICAL REVERSE CHARACTERISTICS

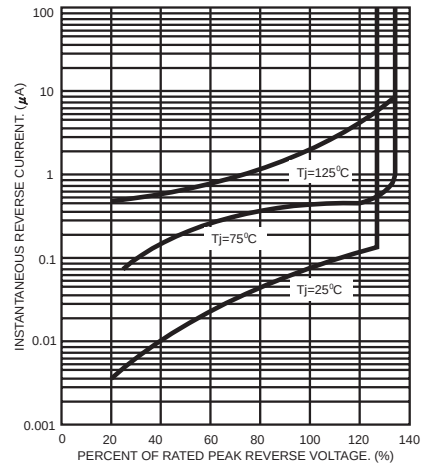


FIG.3- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

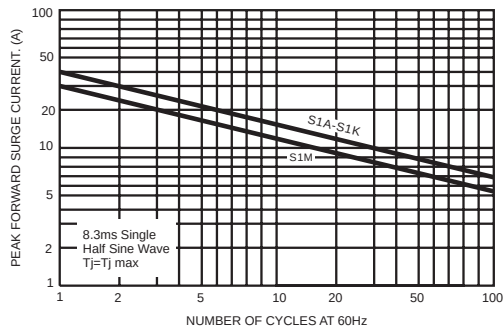


FIG.5- TYPICAL FORWARD CHARACTERISTICS

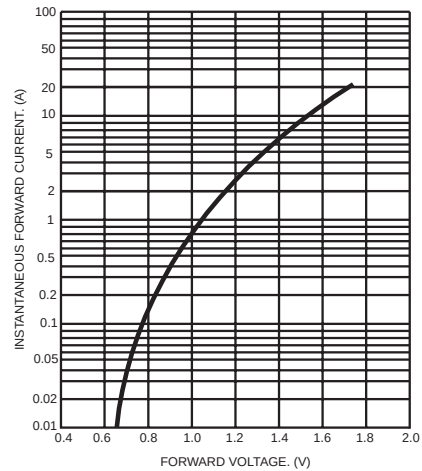


FIG.4- TYPICAL JUNCTION CAPACITANCE

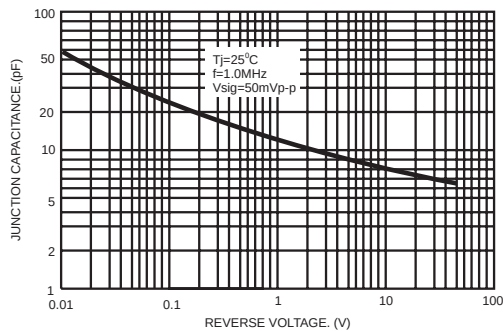


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

